



TDA7850

4 x 50W MOSFET Quad bridge power amplifier plus HSD

Features

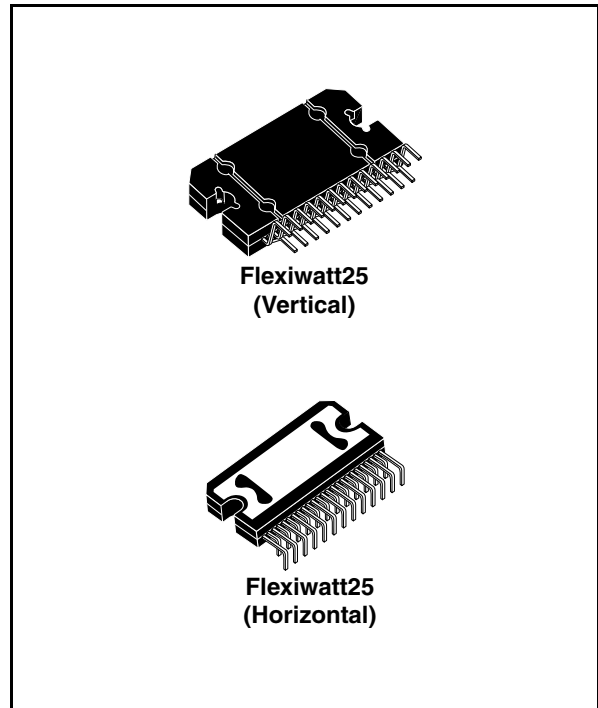
- Superior output power capability:
 - 4 x 50W/4Ω Max.
 - 4 x 30W/4Ω @ 14.4V, 1KHz, 10%
 - 4 x 80W/2Ω Max.
 - 4 x 55W/2Ω @ 14.4V, 1KHz, 10%
- MOSFET Output power stage
- Excellent 2Ω driving capability
- HI-FI class distortion
- Low output noise
- ST-BY Function
- Mute function
- Automute at min. supply voltage detection
- Low external component count:
 - Internally fixed gain (26dB)
 - No external compensation
 - No bootstrap capacitors
- On board 0.35A high side driver

Protections:

- Output short circuit to GND, to V_S , across the load
- Very inductive loads
- Overrating chip temperature with soft thermal limiter
- Output DC offset detection
- Load dump voltage
- Fortuitous open GND
- Reversed battery
- ESD

Order codes

Part number	Package	Packing
TDA7850	Flexiwatt25 (Vertical)	Tube
TDA7850H	Flexiwatt25 (Horizontal)	Tube



Description

The TDA7850 is a breakthrough MOSFET technology class AB audio power amplifier in Flexiwatt 25 package designed for high power car radio. The fully complementary P-Channel/N-Channel output structure allows a rail to rail output voltage swing, which, combined with high output current and minimised saturation losses, sets new power references in the car-radio field, with unparalleled distortion performances.

The TDA7850 integrates a DC offset detector.

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1 Block diagram and pin description

Figure 1. Block diagram

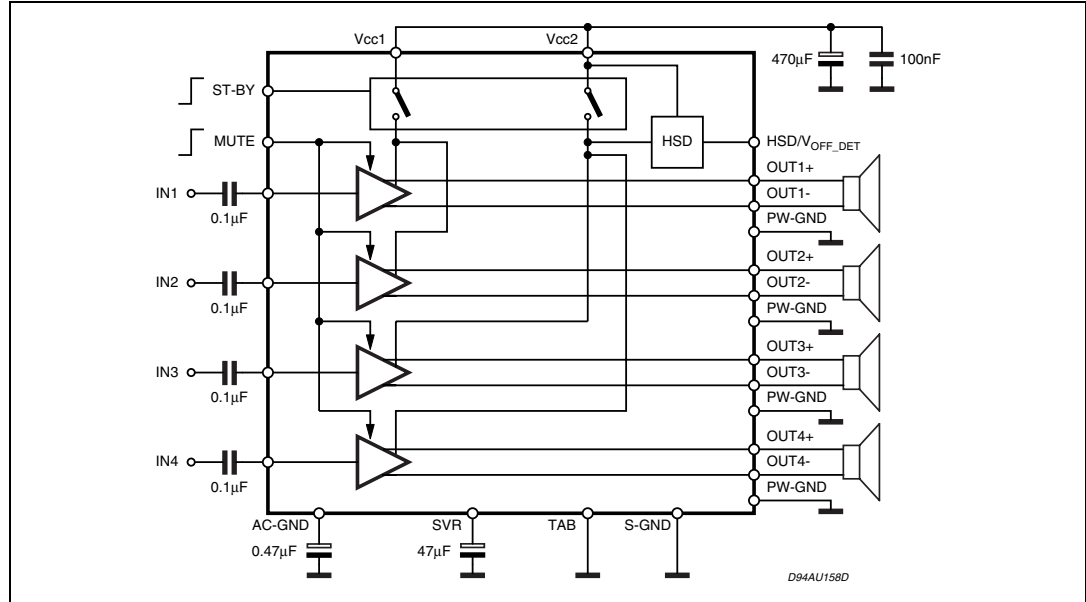
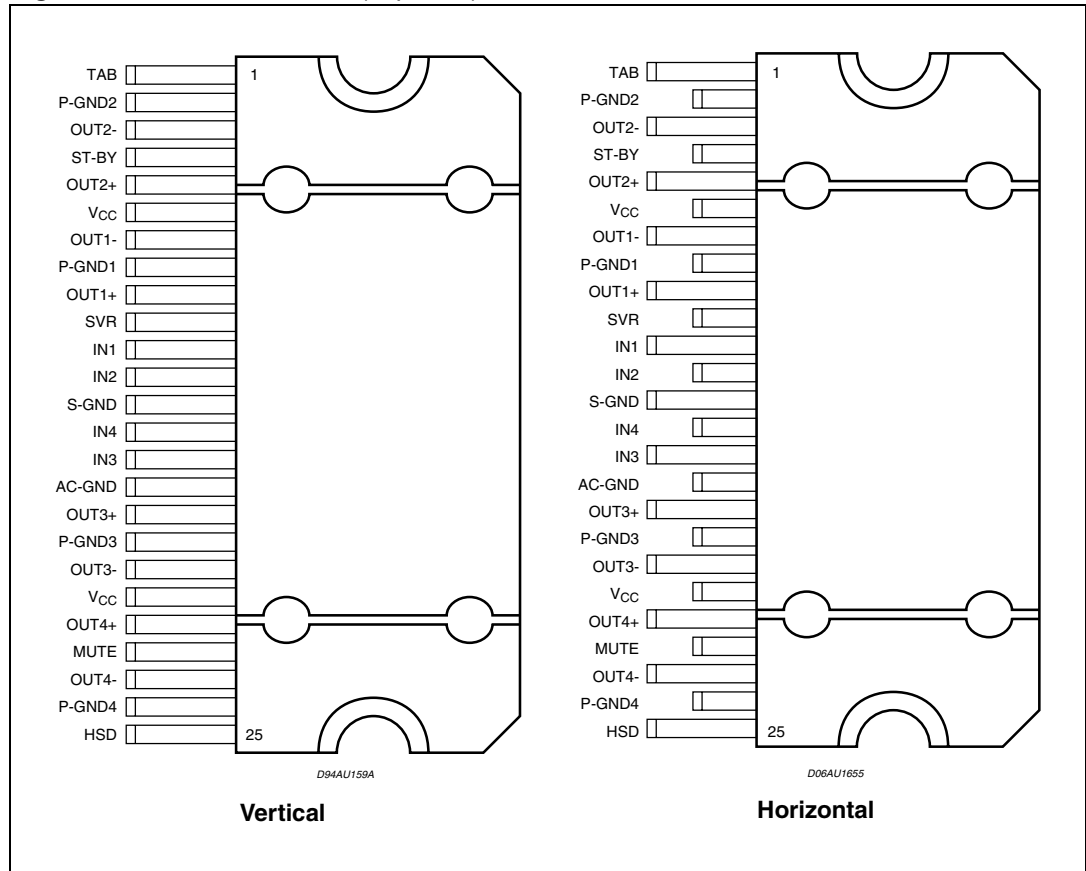


Figure 2. Pin connection (Top view)



2 Electrical specifications

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CC}	Operating supply voltage	18	V
$V_{CC(DC)}$	DC Supply voltage	28	V
$V_{CC(pk)}$	Peak supply voltage (for $t = 50ms$)	50	V
I_O	Output peak current repetitive (duty cycle 10% at $f = 10Hz$) non repetitive ($t = 100\mu s$)	9	A
		10	A
P_{tot}	Power dissipation $T_{case} = 70^\circ C$	80	W
T_j	Junction temperature	150	$^\circ C$
T_{stg}	Storage temperature	-55 to 150	$^\circ C$

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{th j-case}$	Thermal resistance junction to case Max.	1	$^\circ C/W$

Table 3. Electrical characteristics

(Refer to the test and application diagram, $V_S = 13.2V$; $R_L = 4\Omega$; $R_g = 600\Omega$; $f = 1KHz$; $T_{amb} = 25^\circ C$; unless otherwise specified).

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
I_{q1}	Quiescent current	$R_L = \infty$	100	180	280	mA
V_{OS}	Output offset voltage	Play Mode			± 60	mV
dV_{OS}	During mute ON/OFF output offset voltage				± 60	mV
	During St-By ON/OFF output offset voltage				± 60	mV
G_v	Voltage gain		25	26	27	dB
dG_v	Channel gain unbalance				± 1	dB
P_o	Output power	$V_S = 13.2V$; THD = 10%	23	25		W
		$V_S = 13.2V$; THD = 1%	16	19		W
		$V_S = 14.4V$; THD = 10%	28	30		W
		$V_S = 14.4V$; THD = 1%	20	23		W
		$V_S = 13.2V$; THD = 10%, 2Ω	42	45		W
		$V_S = 13.2V$; THD = 1%, 2Ω	32	34		W
		$V_S = 14.4V$; THD = 10%, 2Ω	50	55		W
		$V_S = 14.4V$; THD = 1%, 2Ω	40	43		W
$P_{o max.}$	Max. output power ⁽¹⁾	$V_S = 14.4V$; $R_L = 4\Omega$		50		W
		$V_S = 14.4V$; $R_L = 2\Omega$		80		W

Table 3. Electrical characteristics (continued)(Refer to the test and application diagram, $V_S = 13.2V$; $R_L = 4\Omega$; $R_g = 600\Omega$; $f = 1KHz$; $T_{amb} = 25^\circ C$; unless otherwise specified).

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Unit
THD	Distortion	$P_O = 4W$		0.006	0.05	%
		$P_O = 15W$; $R_L = 2\Omega$		0.015	0.07	%
e_{No}	Output noise	"A" Weighted		35	50	μV
		$Bw = 20Hz$ to $20KHz$		50	70	μV
SVR	Supply voltage rejection	$f = 100Hz$; $V_r = 1V_{rms}$	50	70		dB
f_{ch}	High cut-off frequency	$P_O = 0.5W$	100	300		KHz
R_i	Input impedance		80	100	120	$K\Omega$
C_T	Cross talk	$f = 1KHz$ $P_O = 4W$	60	70	-	dB
		$f = 10KHz$ $P_O = 4W$		60	-	dB
I_{SB}	St-By Current consumption	$V_{St-By} = 1.5V$			20	μA
		$V_{St-By} = 0$			10	μA
I_{pin5}	St-by pin current	$V_{St-By} = 1.5V$ to $3.5V$			± 10	μA
$V_{SB out}$	St-By Out threshold voltage	(Amp: ON)	3.5			V
$V_{SB in}$	St-By in threshold voltage	(Amp: OFF)			1.5	V
A_M	Mute attenuation	$P_{Oref} = 4W$	80	90		dB
$V_{M out}$	Mute out threshold voltage	(Amp: Play)	3.5			V
$V_{M in}$	Mute in threshold voltage	(Amp: Mute)			1.5	V
$V_{AM in}$	VS automute threshold	(Amp: Mute) $Att \geq 80dB$; $P_{Oref} = 4W$	6.5	7		V
		(Amp: Play) $Att < 0.1dB$; $P_O = 0.5W$		7.5	8	V
I_{pin23}	Muting pin current	$V_{MUTE} = 1.5V$ (Sourced current)	7	12	18	μA
		$V_{MUTE} = 3.5V$	-5		18	μA
HSD section						
$V_{dropout}$	Dropout Voltage	$I_O = 0.35A$; $V_S = 9$ to $16V$		0.25	0.6	V
I_{prot}	Current Limits		400		800	mA
Offset detector (Pin 25)						
V_{M_ON}	Mute voltage for DC offset detection enabled	$V_{stby} = 5V$	8			V
V_{M_OFF}					6	V
V_{OFF}	Detected differential output offset	$V_{stby} = 5V$; $V_{mute} = 8V$	± 2	± 3	± 4	V
V_{25_T}	Pin 25 Voltage for detection = TRUE	$V_{stby} = 5V$; $V_{mute} = 8V$ $V_{OFF} > \pm 4V$	0		1.5	V
V_{25_F}	Pin 25 Voltage for detection = FALSE	$V_{stby} = 5V$; $V_{mute} = 8V$ $V_{OFF} > \pm 2V$	12			V

1. Saturated square wave output.

Figure 3. Standard test and application circuit

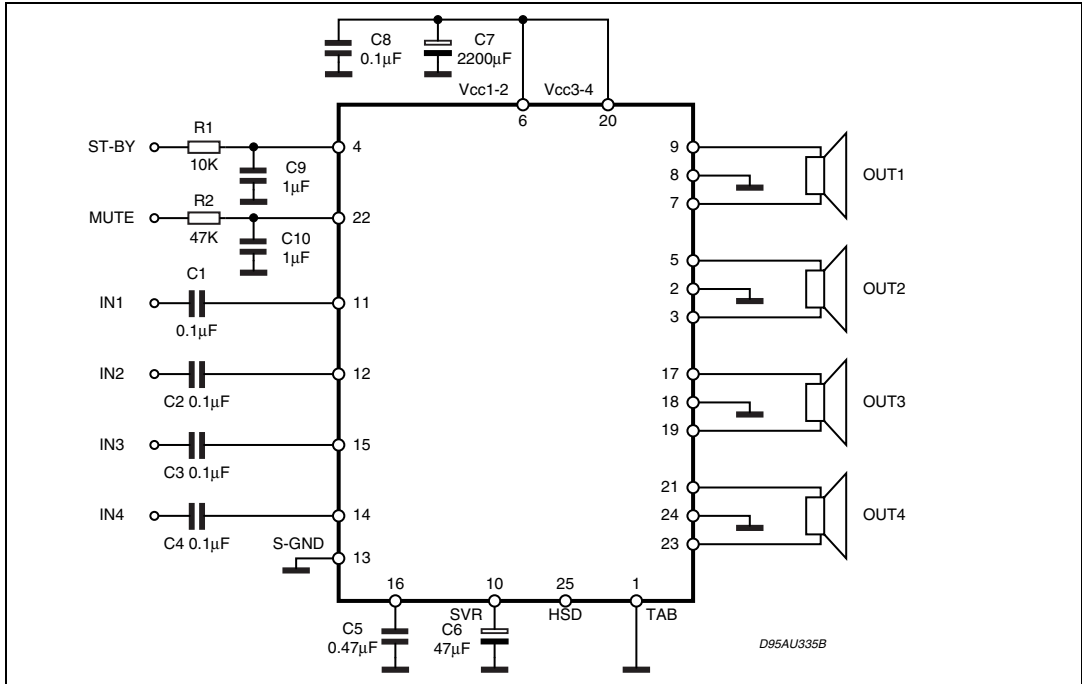
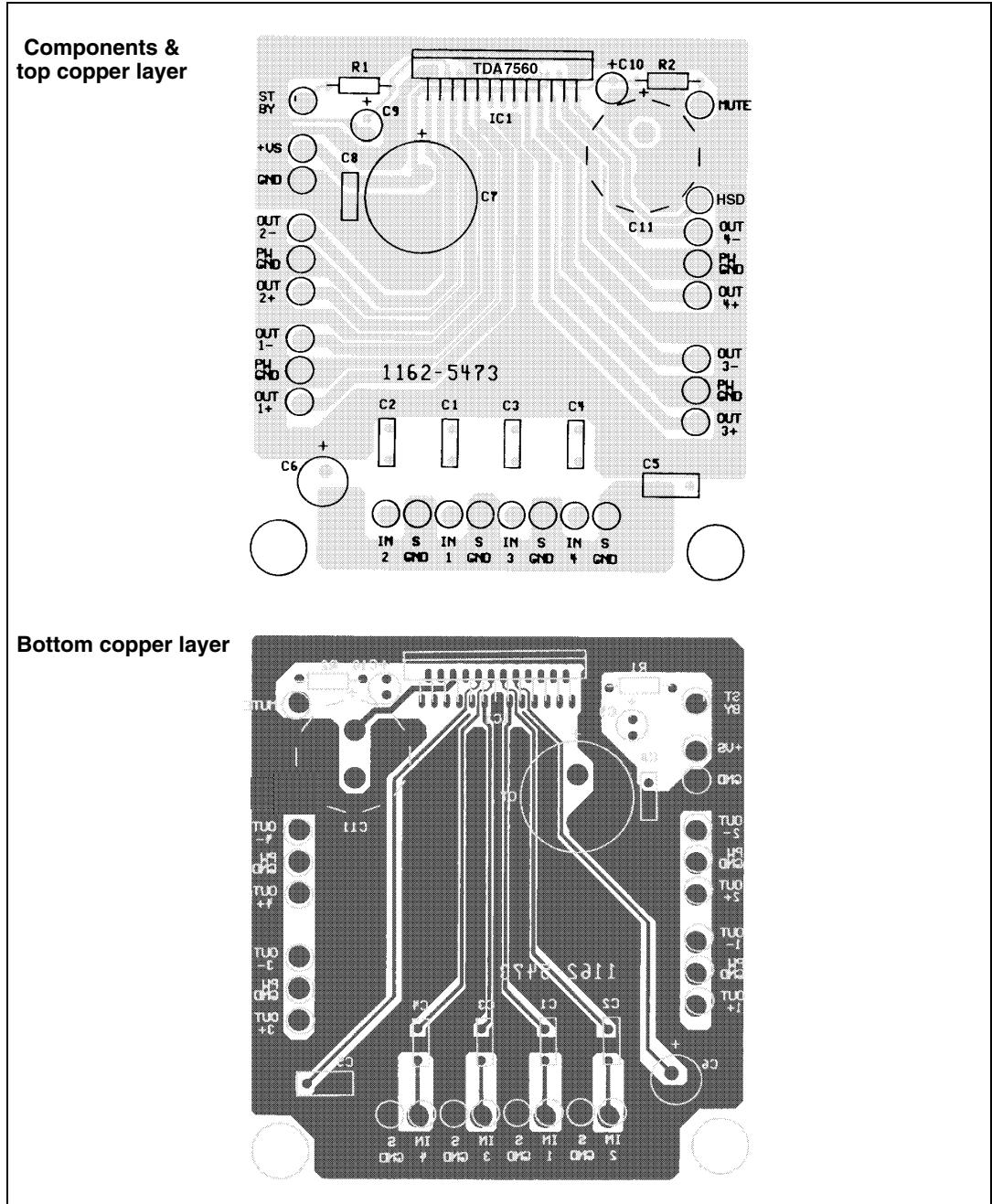


Figure 4. P.C.B. and component layout of the [Figure 3.](#)



3 Application hints (ref. to the circuit of *Figure 3*)

3.1 SVR

Besides its contribution to the ripple rejection, the SVR capacitor governs the turn ON/OFF time sequence and, consequently, plays an essential role in the pop optimization during ON/OFF transients. To conveniently serve both needs, **its minimum recommended value is 10 μ F**.

3.2 Input stage

The TDA7850's inputs are ground-compatible and can stand very high input signals (± 8 Vpk) without any performance degradation.

If the standard value for the input capacitors (0.1 μ F) is adopted, the low frequency cut-off will amount to 16 Hz.

3.3 Stand-by and muting

STAND-BY and MUTING facilities are both CMOS compatible. In absence of true CMOS ports or microprocessors, a direct connection to Vs of these two pins is admissible but a 470 kOhm equivalent resistance should be present between the power supply and the muting and stand-by pins.

R-C cells have always to be used in order to smooth down the transitions for preventing any audible transient noises.

About the stand-by, the time constant to be assigned in order to obtain a virtually pop-free transition has to be slower than 2.5V/ms.

3.4 DC offset detector

The TDA7850 integrates a DC offset detector to avoid an anomalous DC offset on the inputs of the amplifier which may be multiplied by the gain, and result in a dangerous large offset on the outputs, which may lead to speaker damage through overheating.

The feature is enabled by the MUTE pin and works with the amplifier unmuted and with no signal on the inputs. The DC offset detection is signaled out on the HSD pin.

3.5 Heatsink definition

Under normal usage (4 Ohm speakers) the heatsink's thermal requirements have to be deduced from fig. 18, which reports the simulated power dissipation when real music/speech programmes are played out. Noise with gaussian-distributed amplitude was employed for this simulation. Based on that, frequent clipping occurrence (worst-case) will cause $P_{diss} = 26$ W. Assuming $T_{amb} = 70^{\circ}\text{C}$ and $T_{CHIP} = 150^{\circ}\text{C}$ as boundary conditions, the heatsink's thermal resistance should be approximately 2 $^{\circ}\text{C}/\text{W}$. This would avoid any thermal shutdown occurrence even after long-term and full-volume operation.

4 Package Information

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark.

ECOPACK specifications are available at: www.st.com.

Figure 5. Flexiwatt25 (vertical) mechanical data & package dimensions

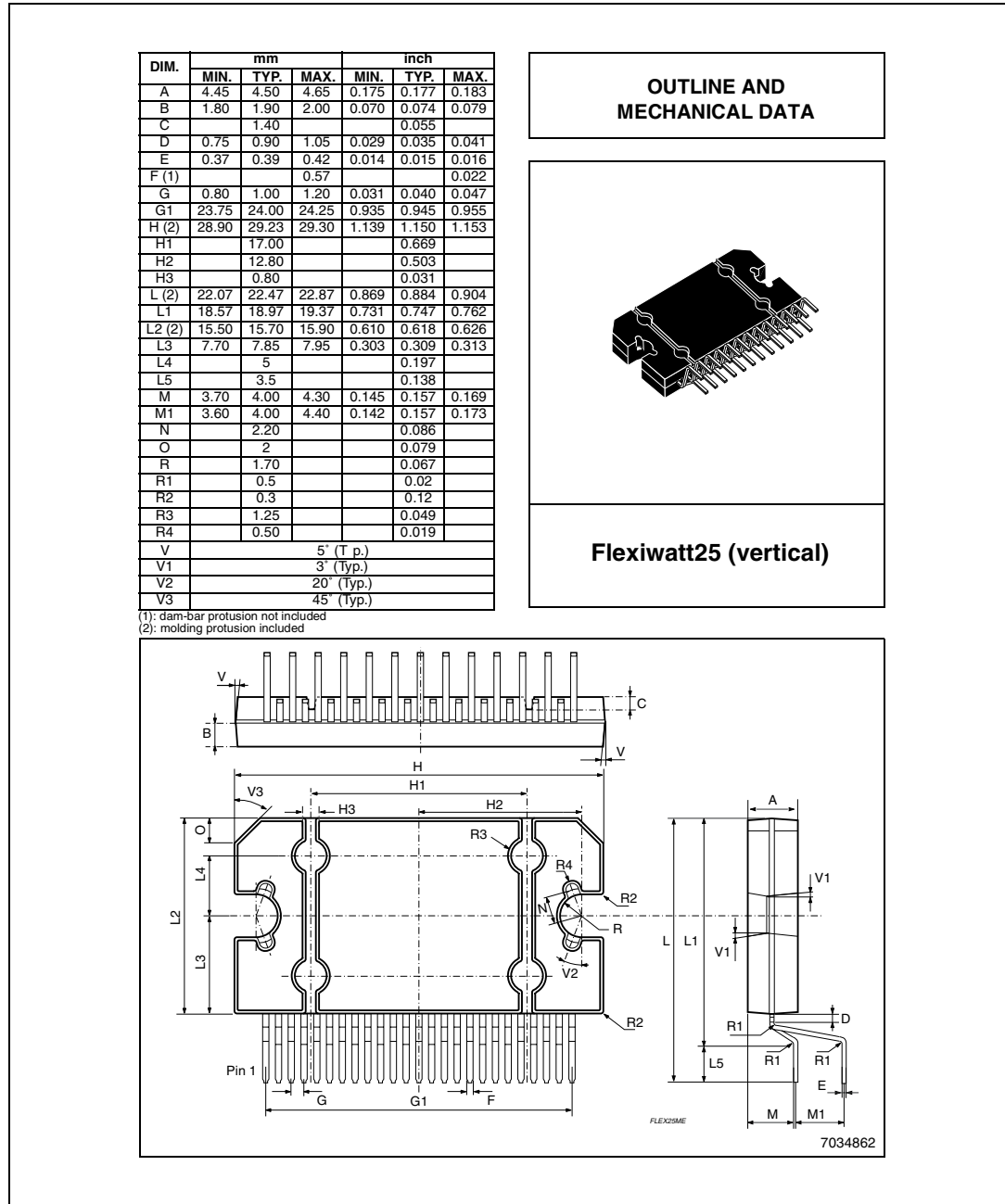
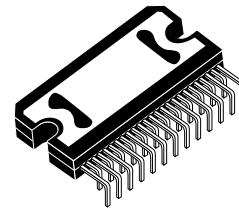


Figure 6. Flexiwatt25 (horizontal) mechanical data & package dimensions

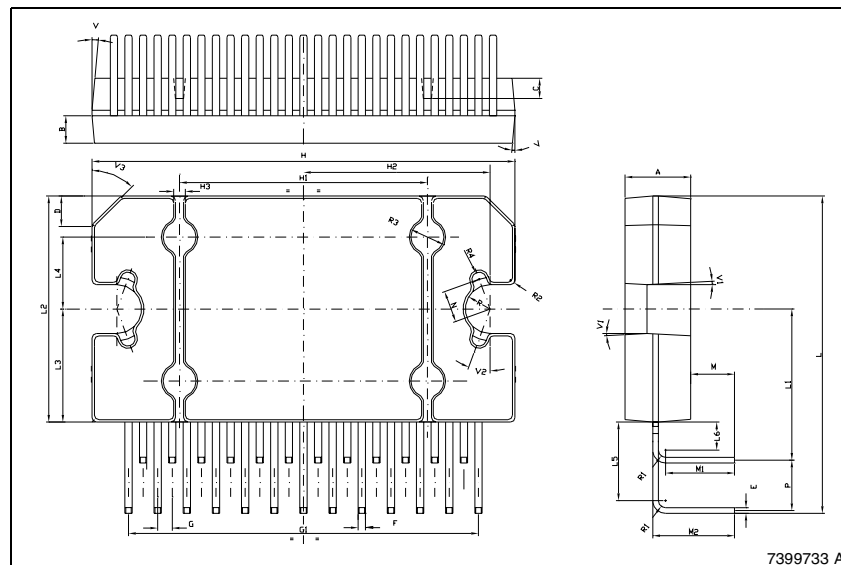
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.45	4.50	4.65	0.175	0.177	0.183
B	1.80	1.90	2.00	0.070	0.074	0.079
C		1.40			0.055	
D		2.00			0.079	
E	0.37	0.39	0.42	0.014	0.015	0.016
F (1)			0.57			0.022
G	0.75	1.00	1.25	0.029	0.040	0.049
G1	23.70	24.00	24.30	0.933	0.945	0.957
H (2)	28.90	29.23	29.30	1.139	1.150	1.153
H1		17.00			0.669	
H2		12.80			0.503	
H3		0.80			0.031	
L (2)	21.64	22.04	22.44	0.852	0.868	0.883
L1	10.15	10.5	10.85	0.40	0.413	0.427
L2 (2)	15.50	15.70	15.90	0.610	0.618	0.626
L3	7.70	7.85	7.95	0.303	0.309	0.313
L4		5			0.197	
L5	5.15	5.45	5.85	0.203	0.214	0.23
L6	1.80	1.95	2.10	0.070	0.077	0.083
M	2.75	3.00	3.50	0.108	0.118	0.138
M1		4.73			0.186	
M2		5.61			0.220	
N		2.20			0.086	
P	3.20	3.50	3.80	0.126	0.138	0.15
R		1.70			0.067	
R1		0.50			0.02	
R2		0.30			0.12	
R3		1.25			0.049	
R4		0.50			0.02	
V	5° (Typ.)					
V1	3° (Typ.)					
V2	20° (Typ.)					
V3	45° (Typ.)					

(1): dam-bar protrusion not included; (2): molding protrusion included

OUTLINE AND MECHANICAL DATA



Flexiwatt25 (Horizontal)



5 Revision history

Table 4. Revision History

Date	Revision	Description of Changes
22-Nov-2006	1	First issue

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